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TI Fine **copper** alloy wire with high strength and flexibility

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AB The **Cu** alloys contain **Sn** 0.1-1, **Ag** 0.1-0.49, and optionally P, Zn, and/or Mn \leq 0.2%. An ingot is scalped, hot worked, annealed at 550°, pickled, drawn 99.96% to 0.15 mm, and straightened. The yield strength is 77.2-80.3, tensile strength 87.9-89.7 kg/mm², elec. conductivity 64.8-84.7% IACS, flexibility good, and drawability satisfactory, compared with 72.1, 74.3 kg/mm², 30.8%, bad, and difficult to 89.8% for the conventional **Cu** alloy containing Ni 1.98 and Mn 0.48%. A typical **Cu** alloy [84506-98-9] contains **Sn** 0.11 and **Ag** 0.49%.